



## Description

The ESD5411N protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN1006-2L

## Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 80 Watts @ 8 x 20  $\mu$ s Pulse
- Low Leakage
- ★ Response Time is Typically < 1 ns
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ IEC61000-4-4 Level 4 EFT Protection
- ★ We declare that the material of product compliance with RoHS requirements.



Circuit Diagram

## Ordering information

Product ID	Pack	Qty(PCS)
ESD5411N	DFN1006-2L	10000

## Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20 $\mu$ s)	130	W
T <sub>L</sub>	Maximum lead temperature for soldering during 10s	260	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>op</sub>	Operating Temperature Range	-40 to +125	°C
T <sub>j</sub>	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	±20 ±15
	IEC61000-4-4 (EFT)		KV
		40	A



**Electrical Characteristics** Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Device	$V_{RWM}$ (V)	$I_R(uA)$ @ $V_{RWM}$	$V_{BR}$ (V) @ $I_T$ (Note 1)		$I_T$ mA	$V_C$ (V) @ $I_{PP}=3$ A*	$V_C$ (V) @ Max $I_{PP}$ *	$I_{PP}$ (A)*	$P_{PK}$ (W)*	$C$ (pF)
	Max	Max	Min	Max		Typ	Max			
ESD5411N	7.0	1.0	7.2	9	1.0	13	17	9	153	8

\*Surge current waveform per Figure 2.

1.  $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of 25°C.

**Typical Characteristics**

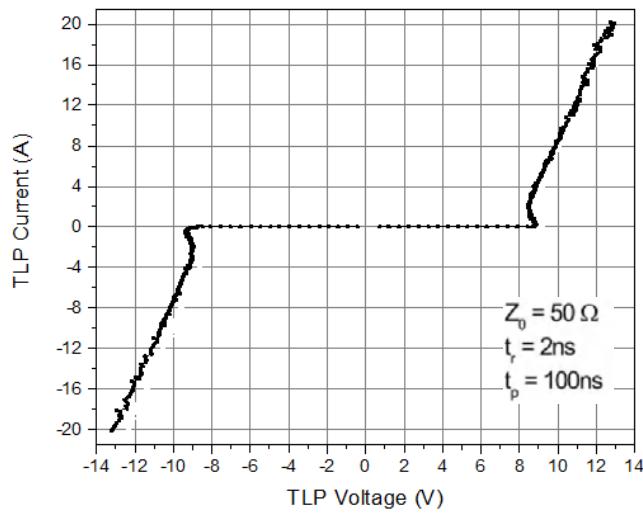


Fig1.TLP Measurement

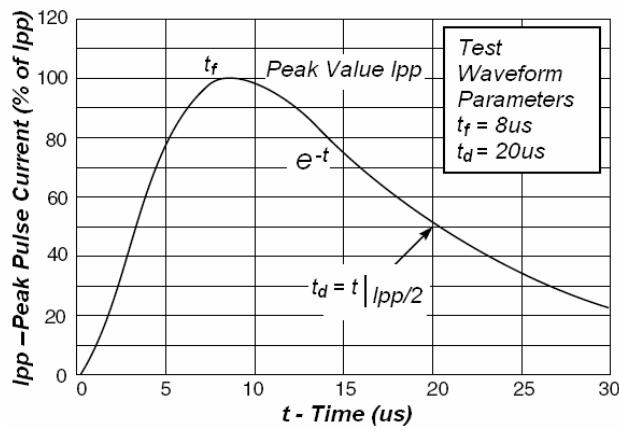


Fig2. Pulse Waveform

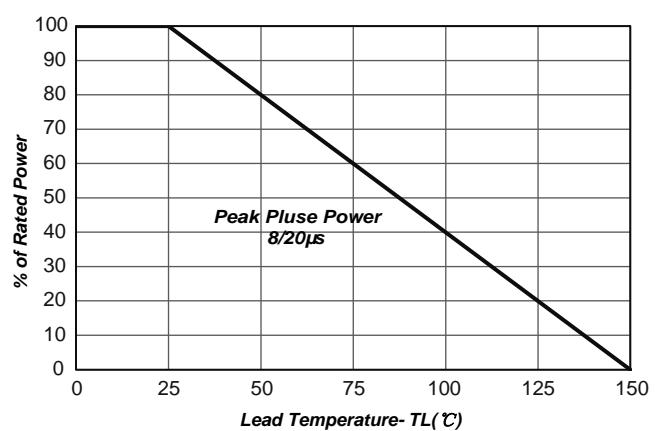
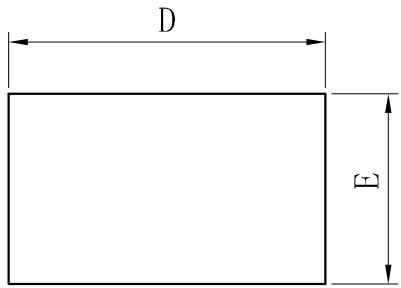


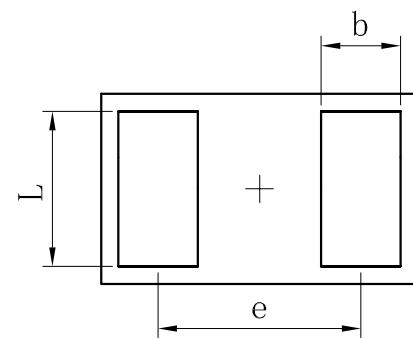
Fig3.Power Derating Curve



## Outline And Dimensions

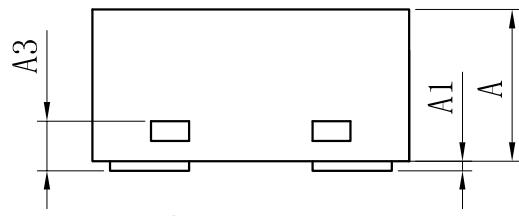


TOP VIEW



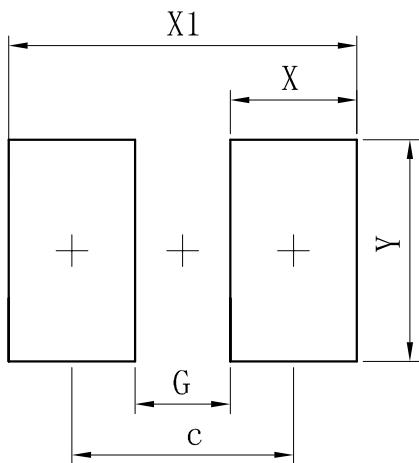
BOTTOM VIEW

DFN1006-2L			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	—	0.64	—
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	—	0.05
A3	0.127REF.		
All Dimensions in mm			



SIDE VIEW

## Soldering Footprint



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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